

We detect:

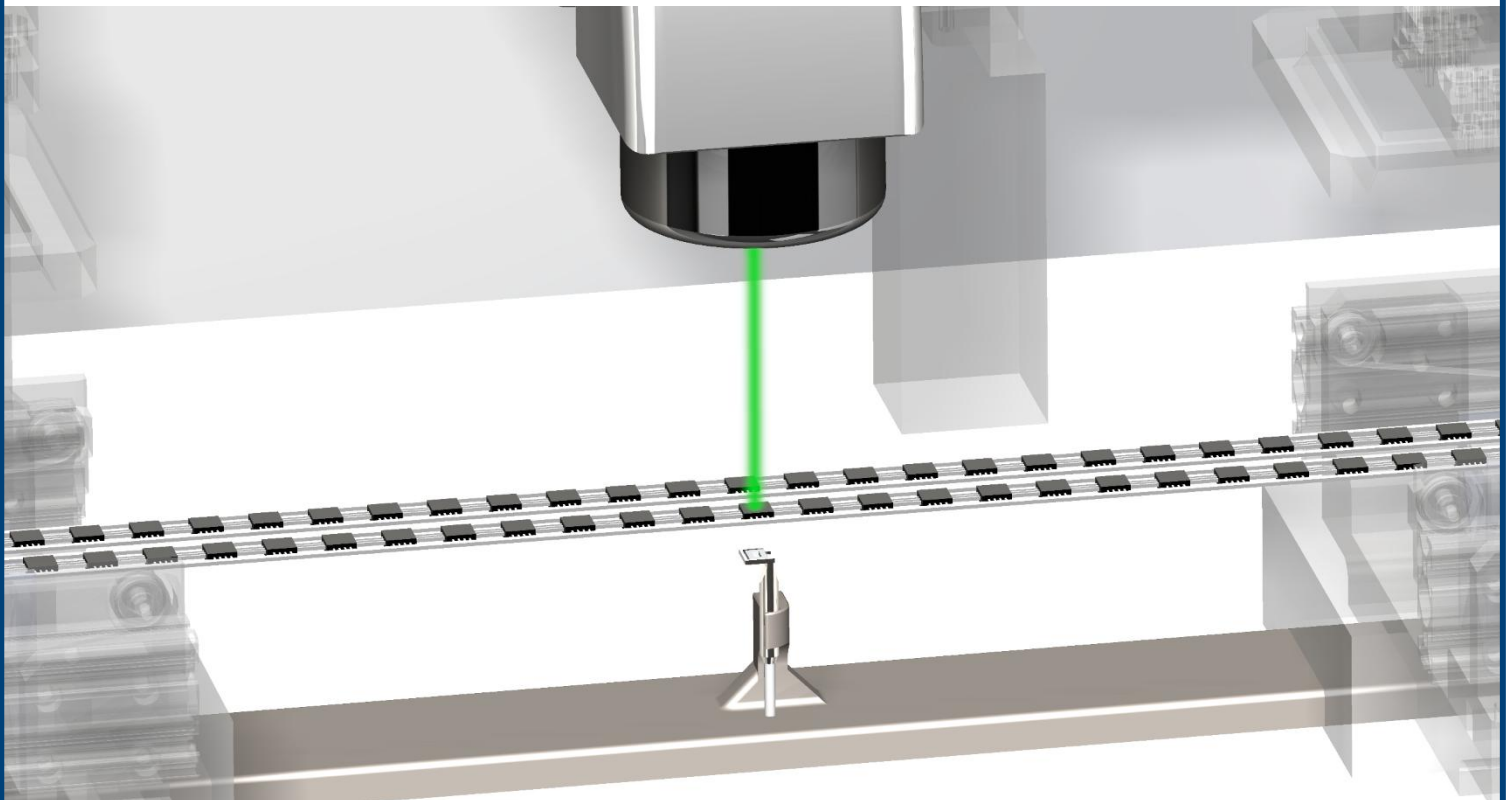
*Cracks in multilayer
ceramic capacitors (MLCC)*

*Delaminations in MEMS
devices (e.g., gas sensors)*

*Cracks in pad craters,
glass substrates, and
embedded devices*

High-speed non-contact

Ultrasonic Inline Inspection



hear with light – see with sound

xarion
laser acoustics

Ultra-fast single-shot mode

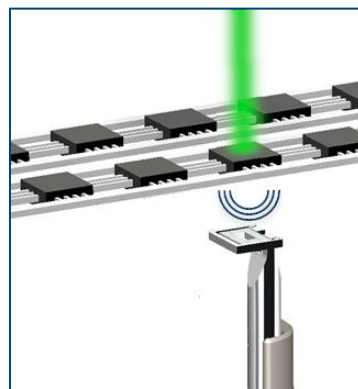
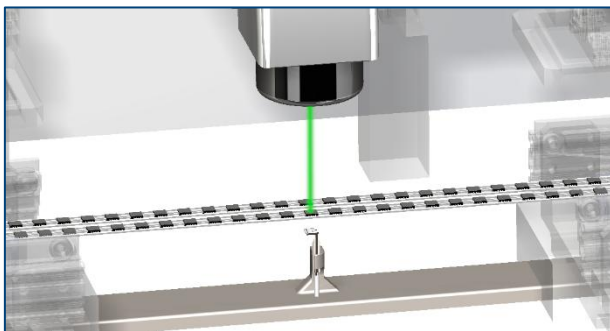
What makes it unique

XARION's laser-based technology enables the ultrasonic inspection of microelectronic components without any coupling liquid.

A single laser pulse generates an acoustic fingerprint of each sample, revealing **internal delaminations and defects** with a throughput of up to 1000 samples per second. The fully non-contact sensor technology can be easily integrated into a high-volume production line, saving costs for offline analysis and ensuring inspection of 100% of the components, e.g., packaged devices for the automotive sector.

Advantages

- **100% documented safety** for your customer
- **Unique non-contact single-shot** ultrasound technology
- **Fully automated** inline inspection of up to 1000 samples per second
- **Easy integration** into high-throughput production environment:
 - **No water coupling**, and no drying of samples necessary
 - No interference with other production steps
- Combination with offline non-contact imaging of defective components for further analysis possible



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